



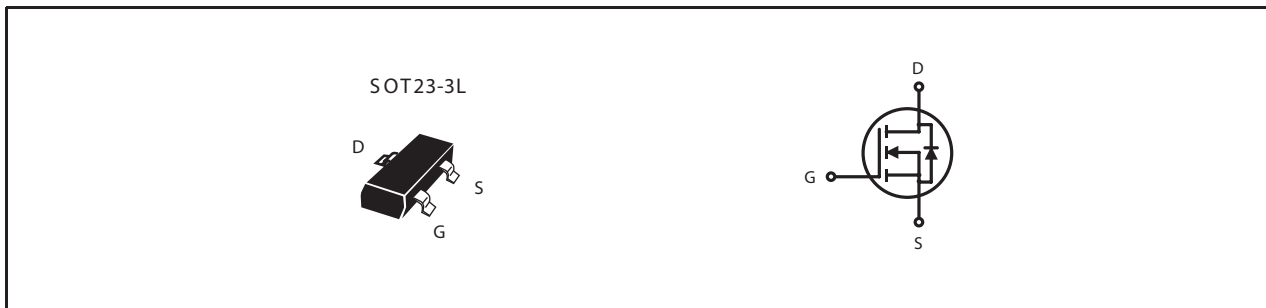
N-Channel Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY

VDSS	ID	RDS(ON) (mΩ) Max
20V	4A	44 @ VGS= 4.5V
		65 @ VGS= 2.5V

FEATURES

- Super high dense cell design for low RDS(ON).
- Rugged and reliable.
- Surface Mount Package.



ABSOLUTE MAXIMUM RATINGS (T_C=25°C unless otherwise noted)

Symbol	Parameter	Limit	Units
V _{DS}	Drain-Source Voltage	20	V
V _{GS}	Gate-Source Voltage	±10	V
I _D	Drain Current-Continuous ^a	T _C =25°C	4
		T _C =70°C	3.2
I _{DM}	-Pulsed ^b	15.3	A
P _D	Maximum Power Dissipation ^a	T _C =25°C	1.25
		T _C =70°C	0.8
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-55 to 150	°C

THERMAL CHARACTERISTICS

Symbol	Parameter	Limit	Units
R _{θJA}	Thermal Resistance, Junction-to-Ambient ^a	100	°C/W

STS2302A

Ver 1.1

ELECTRICAL CHARACTERISTICS (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250μA	20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =16V , V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±10V , V _{DS} =0V			±100	nA
ON CHARACTERISTICS						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.5	0.8	1.5	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V , I _D =4A		35	44	m ohm
		V _{GS} =2.5V , I _D =3.5A		50	65	m ohm
g _{FS}	Forward Transconductance	V _{DS} =5V , I _D =4A		10.5		S
DYNAMIC CHARACTERISTICS [°]						
C _{ISS}	Input Capacitance	V _{DS} =10V, V _{GS} =0V f=1.0MHz		220		pF
C _{OSS}	Output Capacitance			80		pF
C _{RSS}	Reverse Transfer Capacitance			65		pF
SWITCHING CHARACTERISTICS [°]						
t _{D(ON)}	Turn-On Delay Time	V _{DD} =10V I _D =1A		8.5		ns
t _r	Rise Time			14		ns
t _{D(OFF)}	Turn-Off Delay Time	V _{GS} =4.5V		18		ns
t _f	Fall Time	R _{GEN} = 6 ohm		8		ns
Q _g	Total Gate Charge	V _{DS} =10V, I _D =4A, V _{GS} =4.5V		6		nC
Q _{gs}	Gate-Source Charge	V _{DS} =10V, I _D =4A, V _{GS} =4.5V		1.5		nC
Q _{gd}	Gate-Drain Charge			2.5		nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
I _S	Maximum Continuous Drain-Source Diode Forward Current				1	A
V _{SD}	Diode Forward Voltage ^b	V _{GS} =0V, I _S = 1A		0.8	1.2	V

Notes

- a. Surface Mounted on FR4 Board, t ≤ 10sec.
- b. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- c. Guaranteed by design, not subject to production testing.

Dec,31,2010

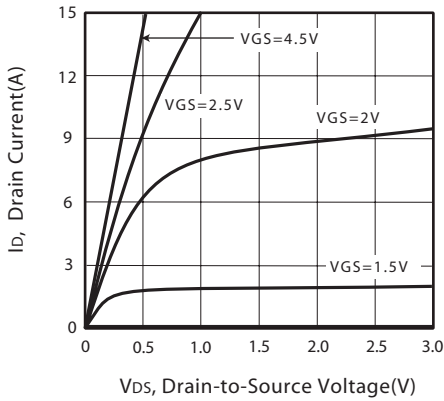


Figure 1. Output Characteristics

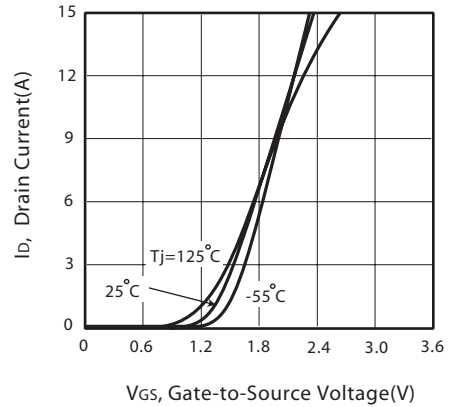


Figure 2. Transfer Characteristics

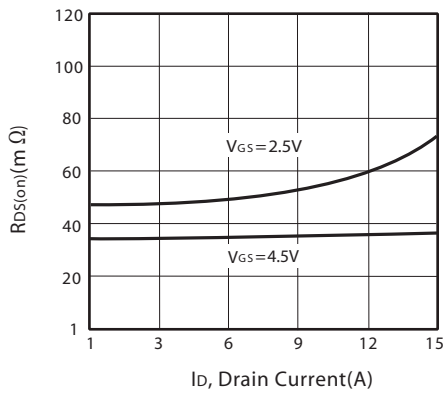


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

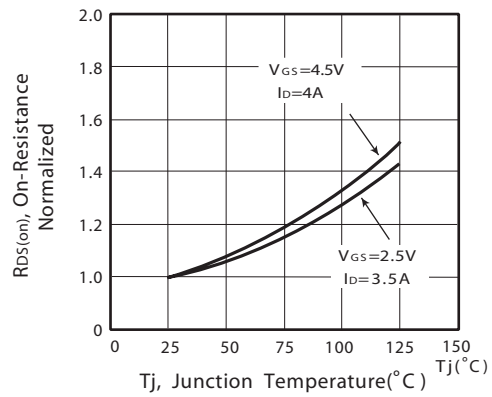


Figure 4. On-Resistance Variation with Drain Current and Temperature

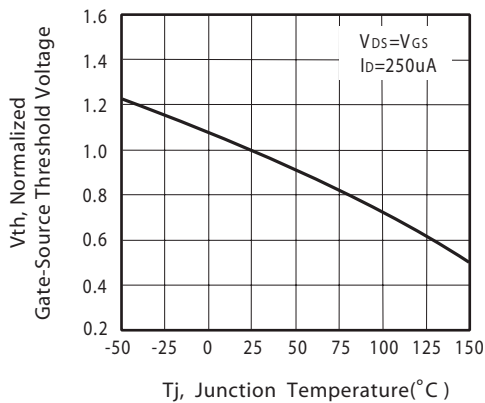


Figure 5. Gate Threshold Variation with Temperature

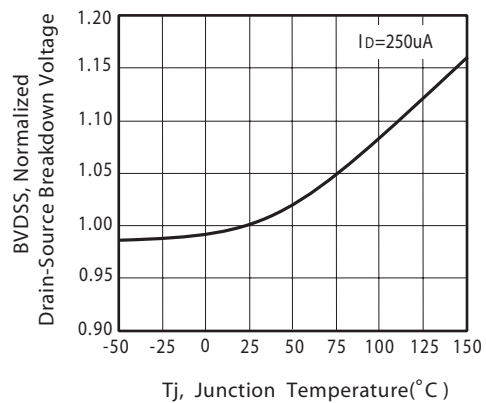


Figure 6. Breakdown Voltage Variation with Temperature

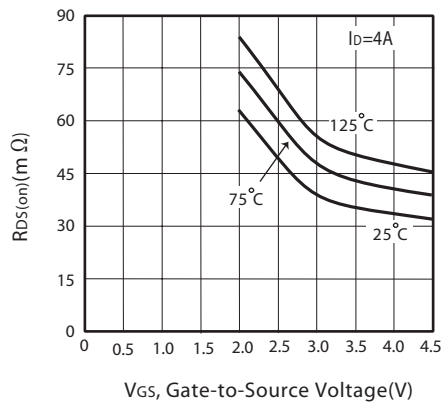


Figure 7. On-Resistance vs. Gate-Source Voltage

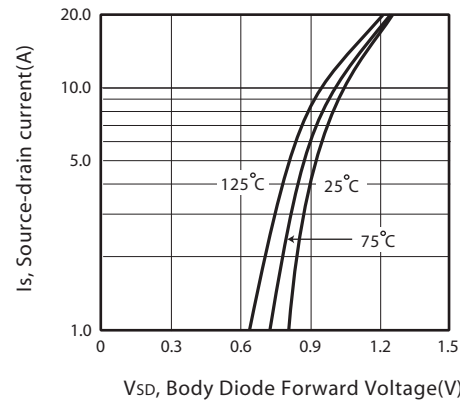


Figure 8. Body Diode Forward Voltage Variation with Source Current

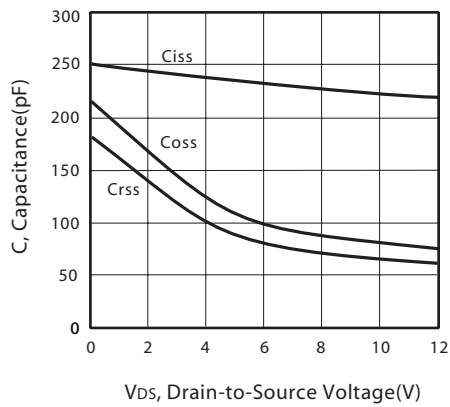


Figure 9. Capacitance

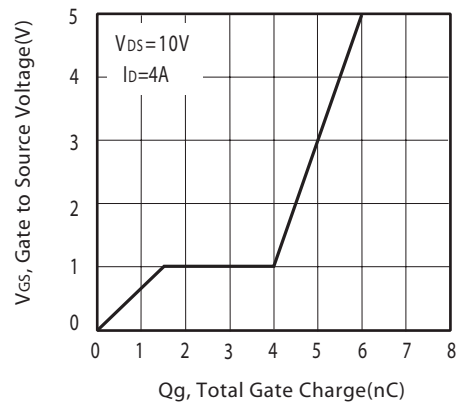


Figure 10. Gate Charge

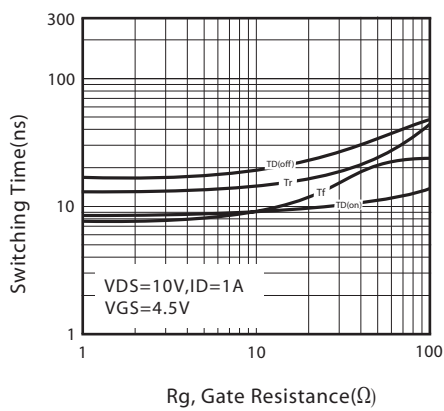


Figure 11. switching characteristics

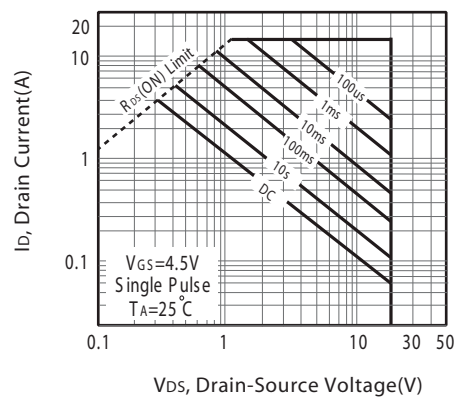


Figure 12. Maximum Safe Operating Area

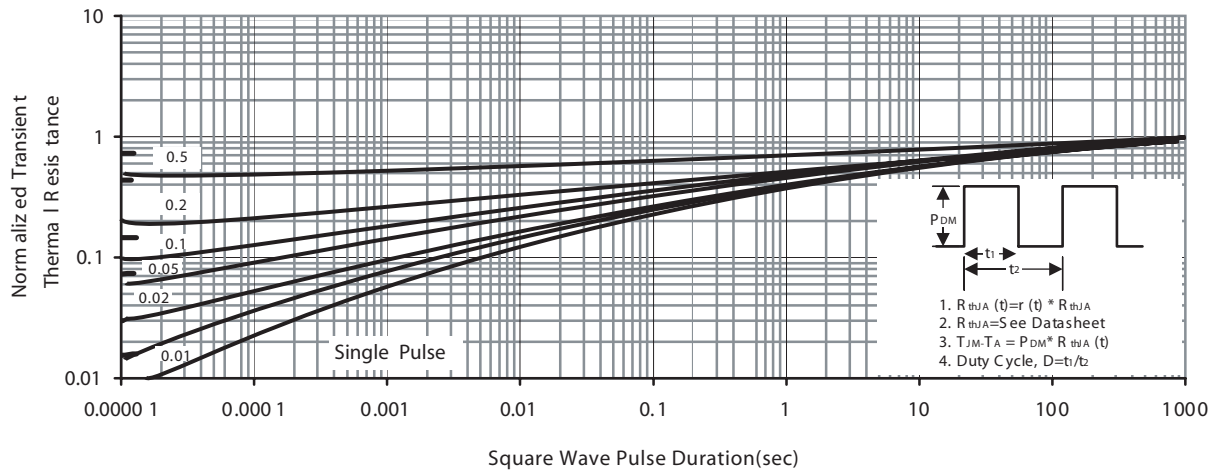
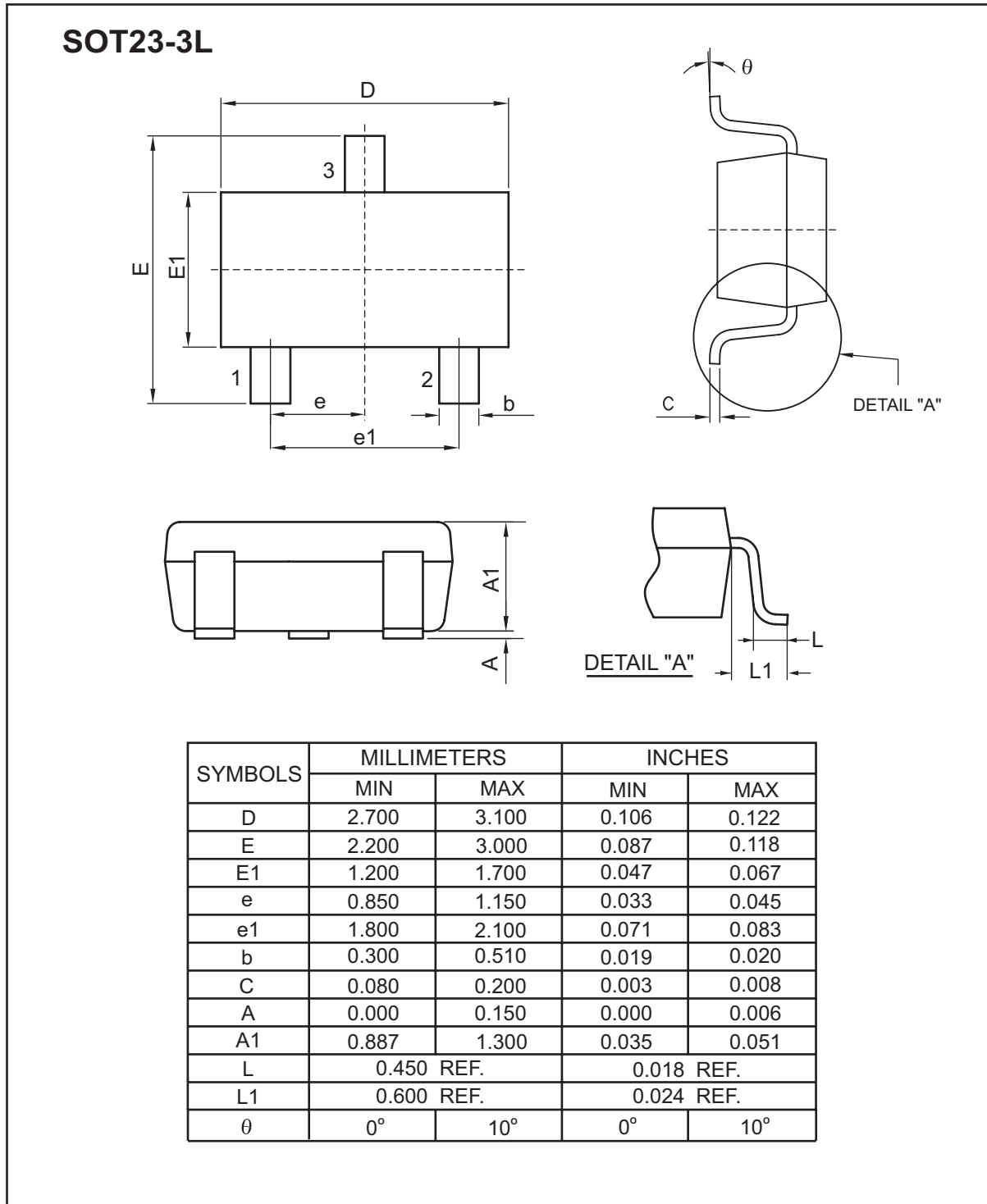


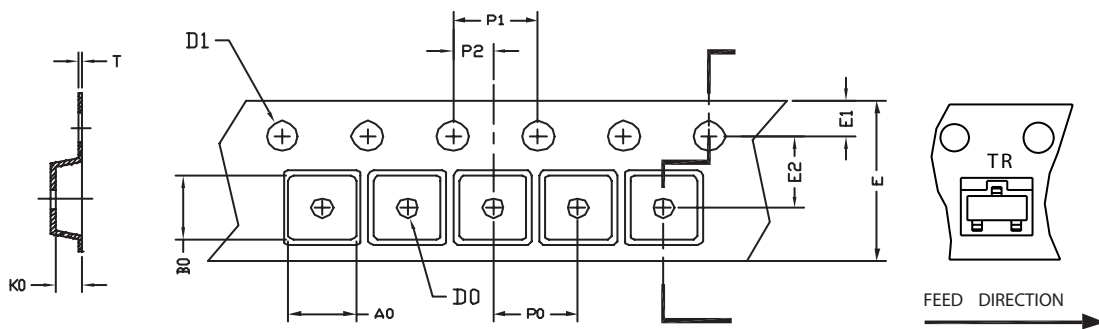
Figure 13. Normalized Thermal Transient Impedance Curve

PACKAGE OUTLINE DIMENSIONS



SOT23-3L Tape and Reel Data

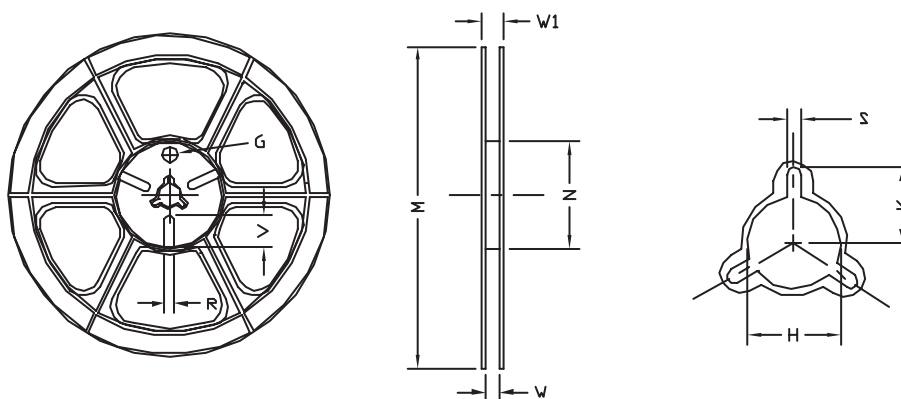
SOT23-3L Carrier Tape



UNIT:mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
SOT23-3L	3.15 ± 0.10	2.77 ± 0.10	1.22 ± 0.10	$\phi 1.00$ $+0.05$	$\phi 1.50$ $+0.10$	8.00 $+0.30$ -0.10	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	0.22 ± 0.04

SOT23-3L Reel



UNIT:mm

TAPE SIZE	REEL SIZE	M	N	W	W1	H	K	S	G	R	V
8mm	$\phi 178$	$\phi 178$ ± 1	$\phi 60$ ± 1	9.00 ± 0.5	12.00 ± 0.5	$\phi 13.5$ ± 0.5	10.5	2.00 ± 0.5	$\phi 10.0$	5.00	18.00